

MOSFETs Silicon N-Channel MOS

SSM3K329R

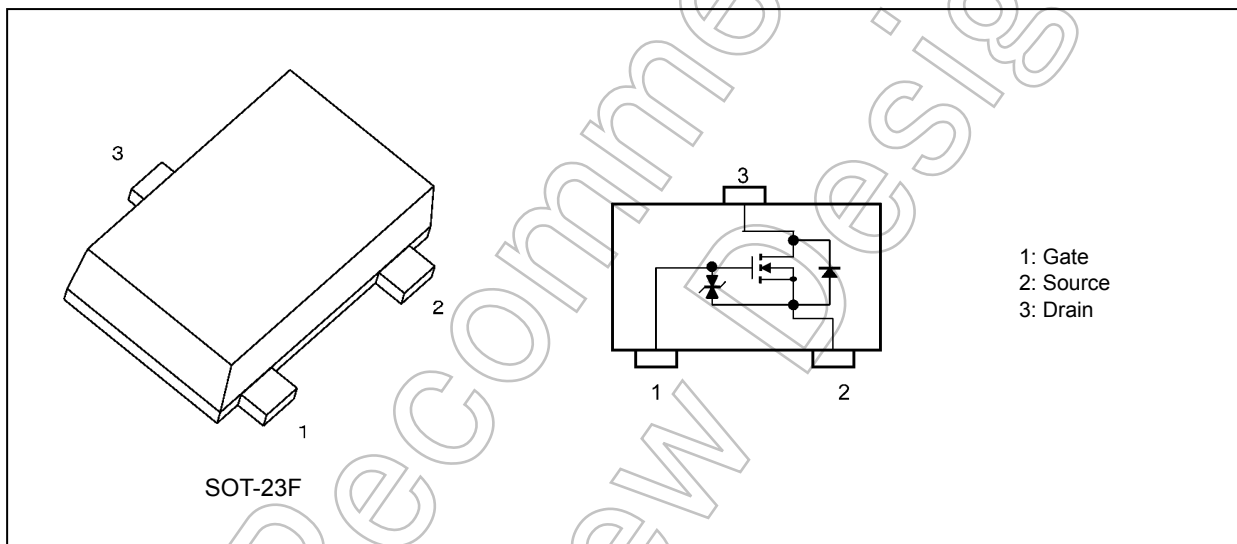
1. Applications

- Power Management Switches
- High-Speed Switching

2. Features

- (1) 1.8-V gate drive voltage.
- (2) Low drain-source on-resistance
 - : $R_{DS(ON)} = 289 \text{ m}\Omega$ (max) (@ $V_{GS} = 1.8 \text{ V}$)
 - $R_{DS(ON)} = 170 \text{ m}\Omega$ (max) (@ $V_{GS} = 2.5 \text{ V}$)
 - $R_{DS(ON)} = 126 \text{ m}\Omega$ (max) (@ $V_{GS} = 4.0 \text{ V}$)

3. Packaging and Internal Circuit



Start of commercial production
2010-02

4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	30	V
Gate-source voltage	V_{GSS}	± 12	V
Drain current (DC) (Note 1)	I_D	3.5	A
Drain current (pulsed) (Note 1), (Note 2)	I_{DP}	7.0	A
Power dissipation (Note 3)	P_D	1	W
Power dissipation (t = 10 s) (Note 3)		2	
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to 150	$^\circ\text{C}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ensure that the channel temperature does not exceed $150\text{ }^\circ\text{C}$.

Note 2: Pulse width (PW) $\leq 10\text{ ms}$, duty $\leq 1\%$

Note 3: Device mounted on an FR4 board. (25.4 mm \times 25.4 mm \times 1.6 mm, Cu pad: 645 mm²)

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, $R_{th(ch-a)}$, and the drain power dissipation, P_D , vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

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5. Electrical Characteristics

5.1. Static Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 12\text{ V}$	—	—	± 1	μA
Drain cut-off current	I_{DSS}	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$	—	—	1	μA
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 1\text{ mA}, V_{GS} = 0\text{ V}$	30	—	—	V
Drain-source breakdown voltage (Note 1)	$V_{(BR)DSX}$	$I_D = 1\text{ mA}, V_{GS} = -12\text{ V}$	18	—	—	V
Gate threshold voltage (Note 2)	V_{th}	$V_{DS} = 3\text{ V}, I_D = 1\text{ mA}$	0.4	—	1.0	V
Drain-source on-resistance (Note 3)	$R_{DS(ON)}$	$I_D = 1.0\text{ A}, V_{GS} = 4.0\text{ V}$	—	96	126	$\text{m}\Omega$
		$I_D = 0.8\text{ A}, V_{GS} = 2.5\text{ V}$	—	118	170	
		$I_D = 0.5\text{ A}, V_{GS} = 1.8\text{ V}$	—	158	289	
Forward transfer admittance (Note 3)	$ Y_{fs} $	$V_{DS} = 3\text{ V}, I_D = 1.0\text{ A}$	2.1	4.2	—	S

Note 1: If a reverse bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

Note 2: Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to be below (1 mA for this device). Then, for normal switching operation, $V_{GS(ON)}$ must be higher than V_{th} , and $V_{GS(OFF)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$.

Take this into consideration when using the device.

Note 3: Pulse measurement.

5.2. Dynamic Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$	—	123	—	pF
Reverse transfer capacitance	C_{rss}		—	18	—	
Output capacitance	C_{oss}		—	43	—	
Switching time (turn-on time)	t_{on}	$V_{DD} = 15\text{ V}, I_D = 1.0\text{ A},$ $V_{GS} = 0\text{ to }2.5\text{ V}, R_G = 4.7\text{ }\Omega$ Duty $\leq 1\%$, Input: $t_r, t_f < 5\text{ ns}$ Common source	—	9.2	—	ns
Switching time (turn-off time)	t_{off}		—	6.4	—	

5.3. Switching Time Test Circuit

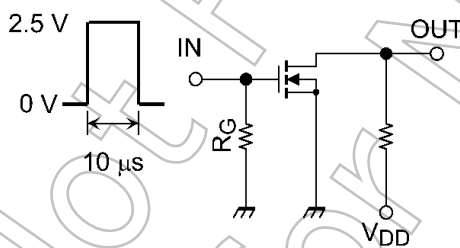


Fig. 5.3.1 Switching Time Test Circuit

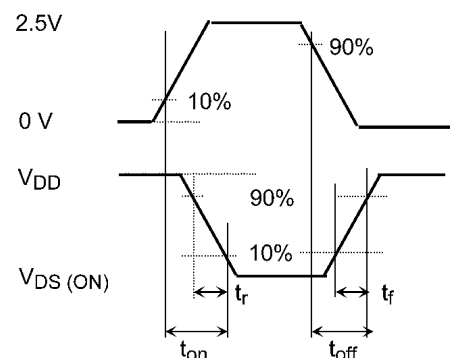


Fig. 5.3.2 Input Waveform/Output Waveform

5.4. Gate Charge Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DS} = 15\text{ V}, I_D = 2.0\text{ A},$ $V_{GS} = 4\text{ V}$	—	1.5	—	nC
Gate-source charge 1	Q_{gs1}		—	0.3	—	
Gate-drain charge	Q_{gd}		—	0.6	—	

5.5. Source-Drain Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Diode forward voltage (Note 1)	V_{DSF}	$I_D = -3.5\text{ A}$, $V_{GS} = 0\text{ V}$	—	-0.9	-1.2	V

Note 1: Pulse measurement.

6. Marking

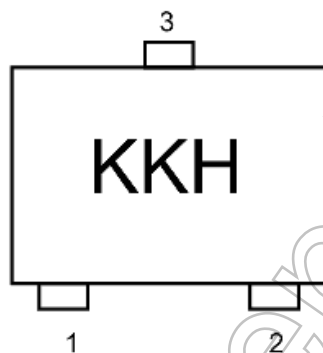


Fig. 6.1 Marking

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7. Characteristics Curves (Note)

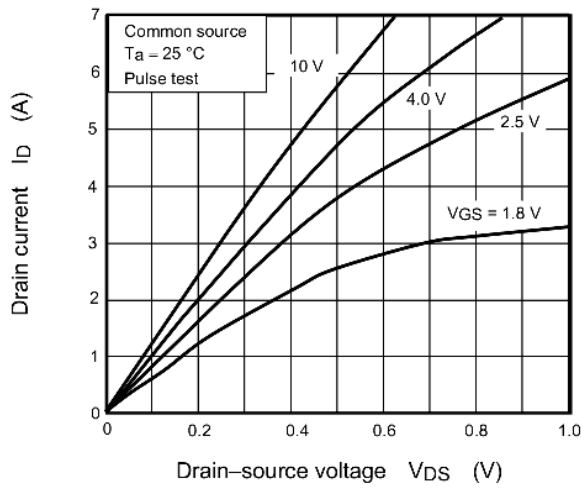


Fig. 7.1 ID - VDS

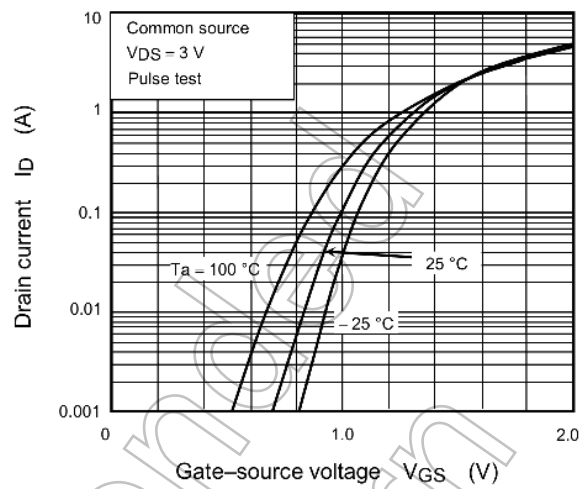


Fig. 7.2 ID - VGS

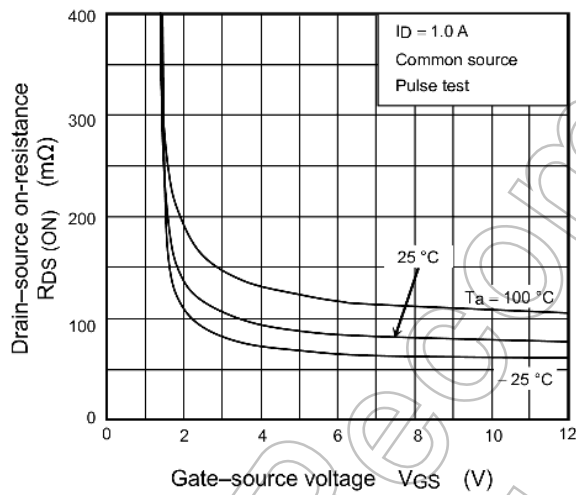


Fig. 7.3 RDS(ON) - VGS

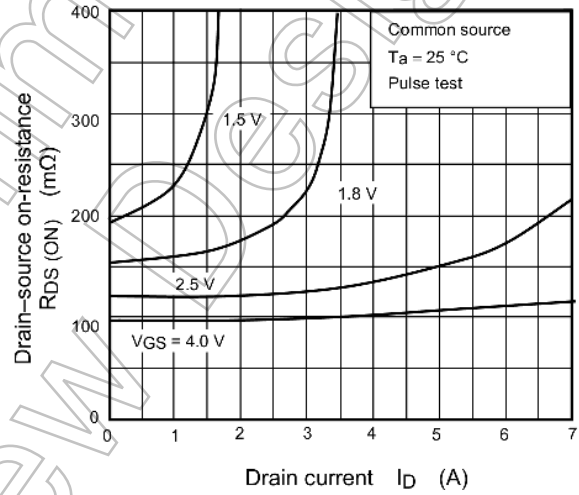


Fig. 7.4 RDS(ON) - ID

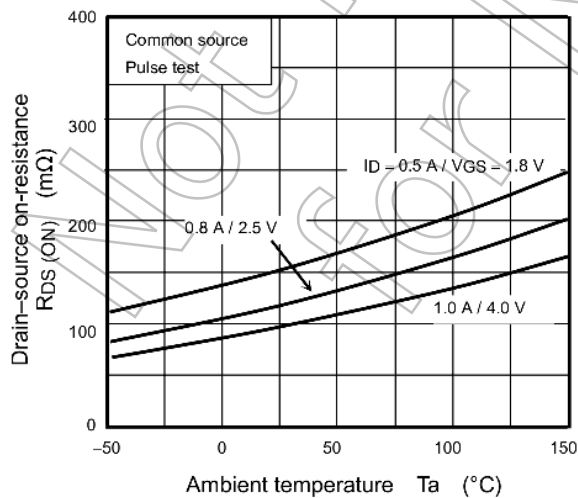


Fig. 7.5 RDS(ON) - Ta

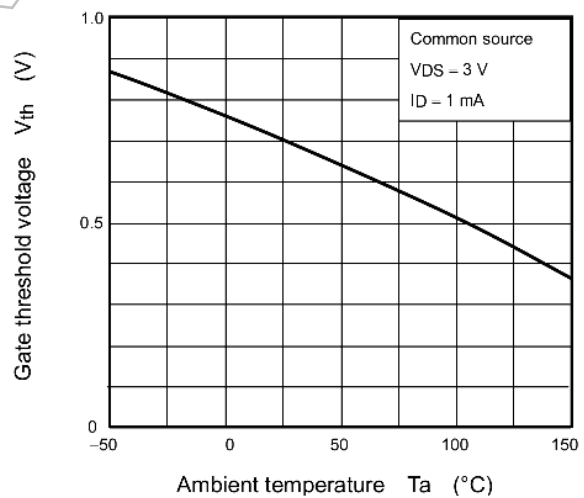


Fig. 7.6 Vth - Ta

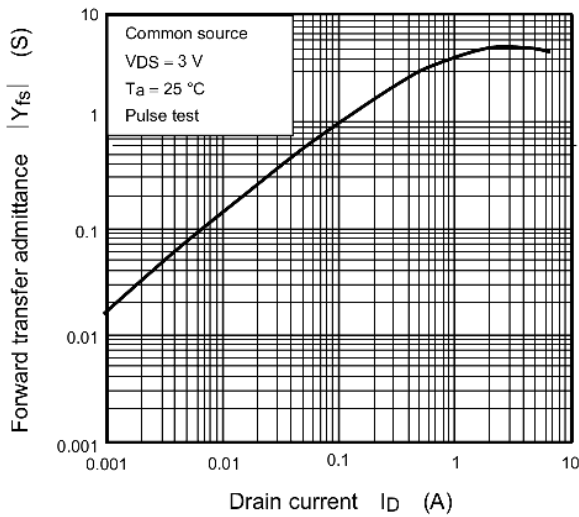


Fig. 7.7 $|Y_{fs}| - I_D$

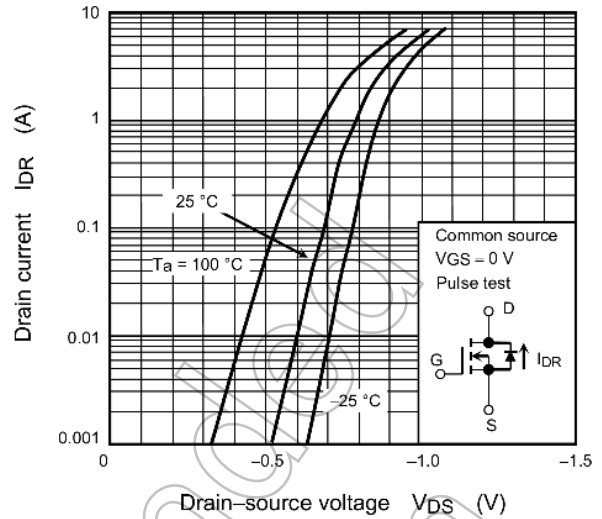


Fig. 7.8 $I_{DR} - V_{DS}$

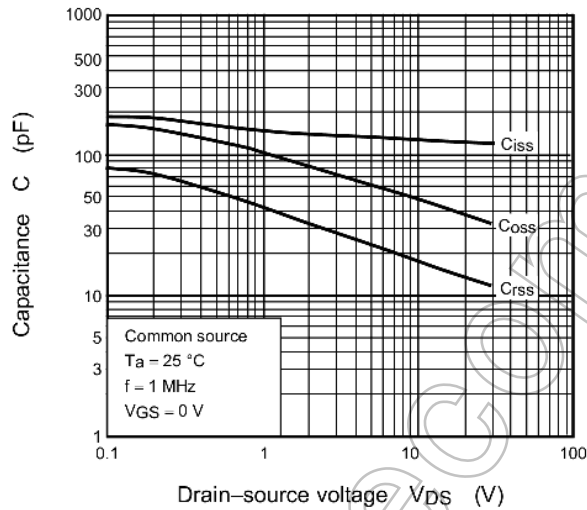


Fig. 7.9 $C - V_{DS}$

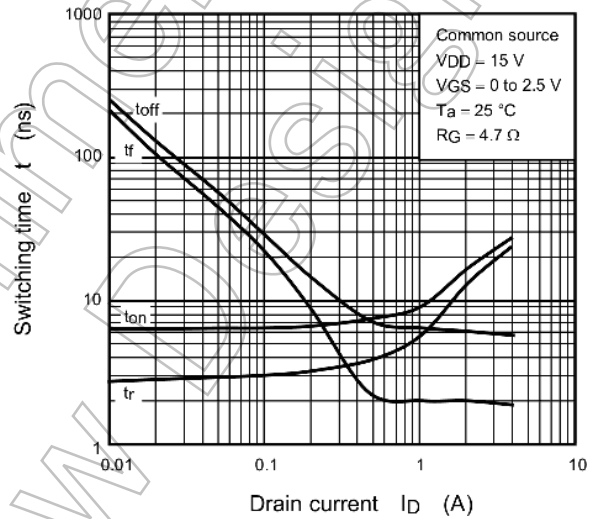


Fig. 7.10 $t - I_D$

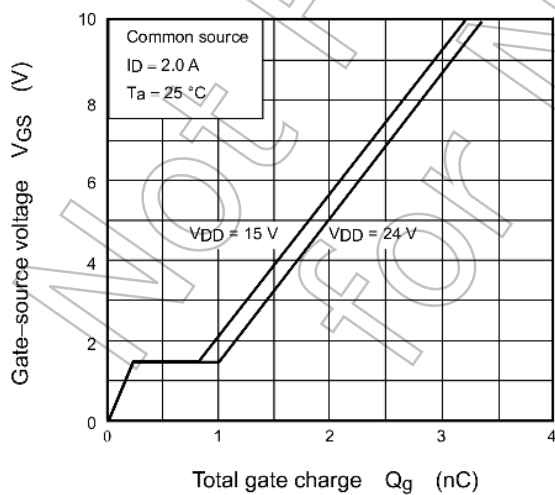


Fig. 7.11 Dynamic Input Characteristics

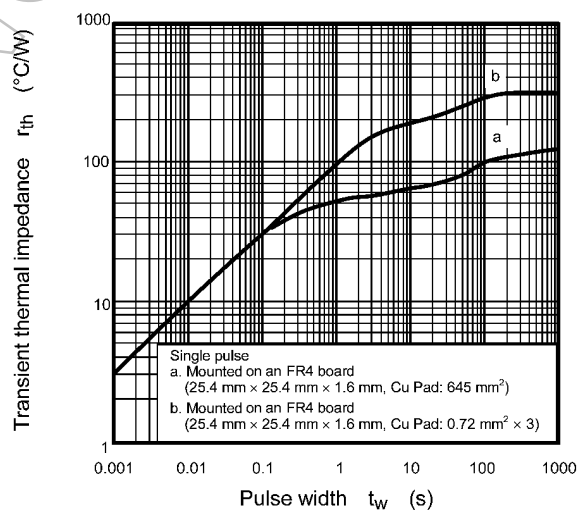


Fig. 7.12 $r_{th} - t_w$

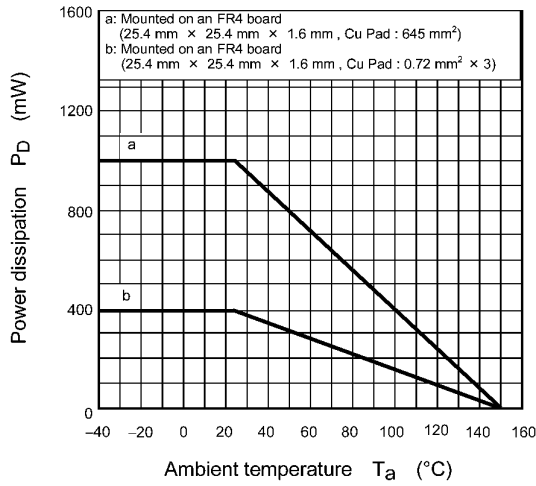


Fig. 7.13 $P_D - T_a$

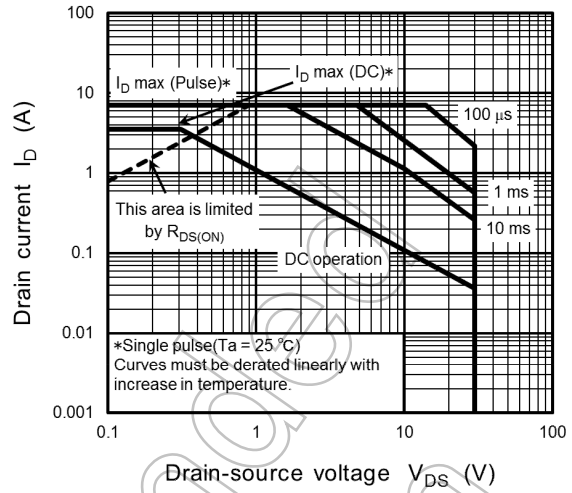


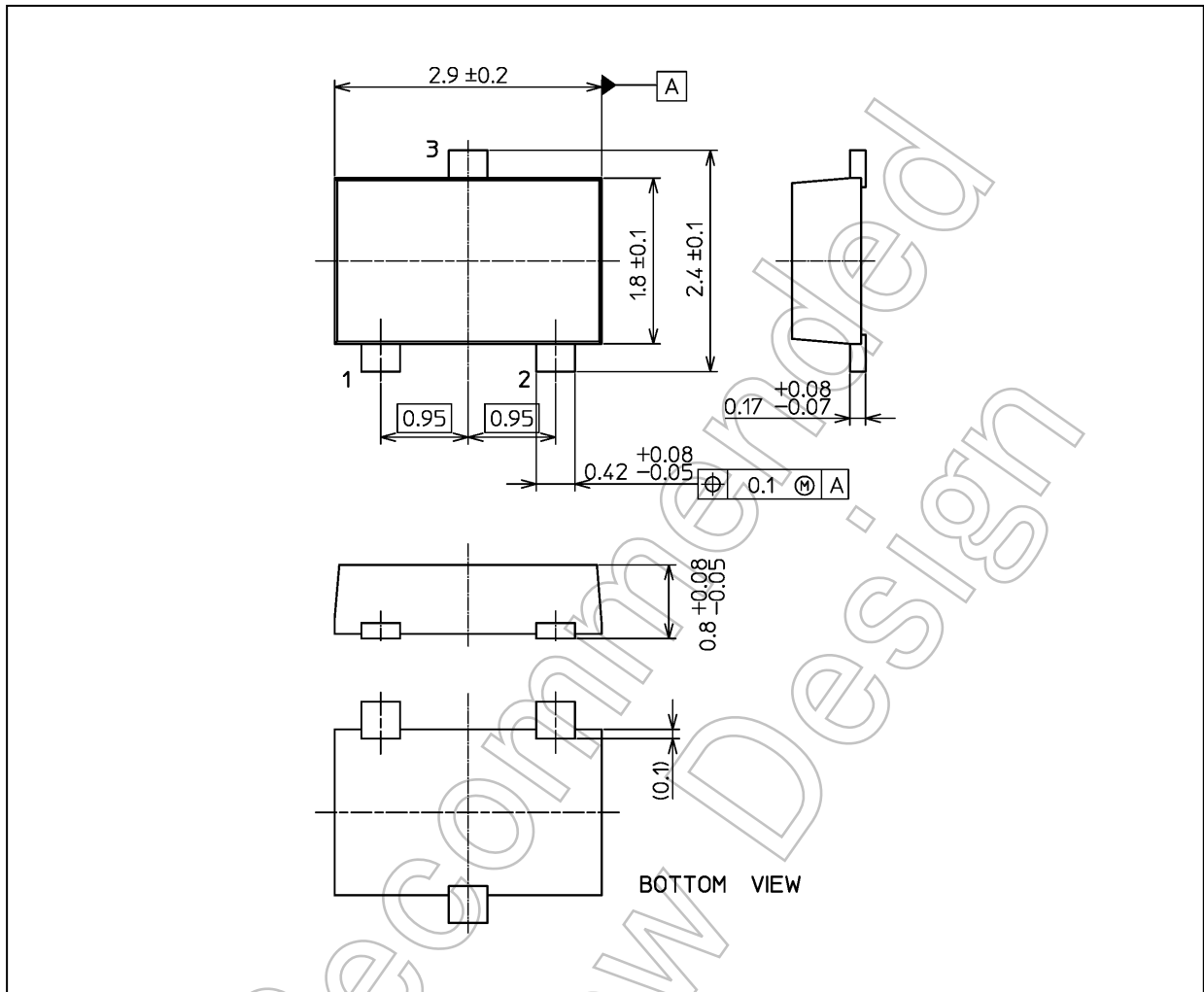
Fig. 7.14 Safe Operating Area

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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Package Dimensions

Unit: mm



Weight: 0.011 g (typ.)

Package Name(s)
Nickname: SOT-23F

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